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Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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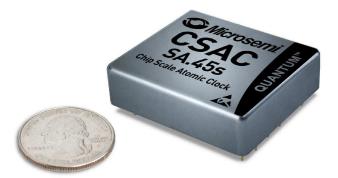


DATASHEET



Quantum[™] SA.45s CSAC

Chip Scale Atomic Clock



Key Features

- Power consumption <120 mW
- Less than 17 cc volume, 1.6" x 1.39" x 0.45"
- 10 MHz CMOS-compatible output
- 1 PPS output and 1 PPS input for synchronization
- RS-232 interface for monitoring and control
- Short term stability (Allan Deviation) of 2.5E-10@ TAU =1 sec

Applications*

- Underwater sensor systems
- GPS receivers
- Backpack radios
- Anti-IED jamming systems
- Autonomous sensor networks
- Unmanned vehicles

*The Chip Scale Atomic Clock is not tested, qualified, and rated for space applications.

With an extremely low power consumption of <120 mW and a volume of <17 cc, the Microsemi® SA.45s Chip Scale Atomic Clock (CSAC) brings the accuracy and stability of an atomic clock to portable applications for the first time.

The SA.45s provides 10 MHz and 1 PPS outputs at standard CMOS levels, with short-term stability (Allan Deviation) of 2.5E-10 @ TAU =1 sec, long-term aging of <9E-10/month, and maximum frequency change of 5E-10 over an operating temperature range of -10°C to +35°C. The SA.45s CSAC accepts a 1 PPS input that may be used to synchronize the unit's 1 PPS output to an external reference clock with ± 100 ns accuracy. The CSAC can also use the 1 PPS input to discipline its phase and frequency to within 1 ns and 1.0E-12, respectively.

A standard CMOS-level RS-232 serial interface is built in to the SA.45s. This is used to control and calibrate the unit and also to provide a comprehensive set of status monitors. The interface is also used to set and read the CSAC's internal timeof-day clock.



Microsemi invented portable atomic timekeeping with QUANTUM[™], the world's first family of miniature and chip scale atomic clocks.

Choose QUANTUM[™] class for best-in-class stability, Size, Weight and Power consumption (SWAP).





Quantum[™] SA.45s CSAC

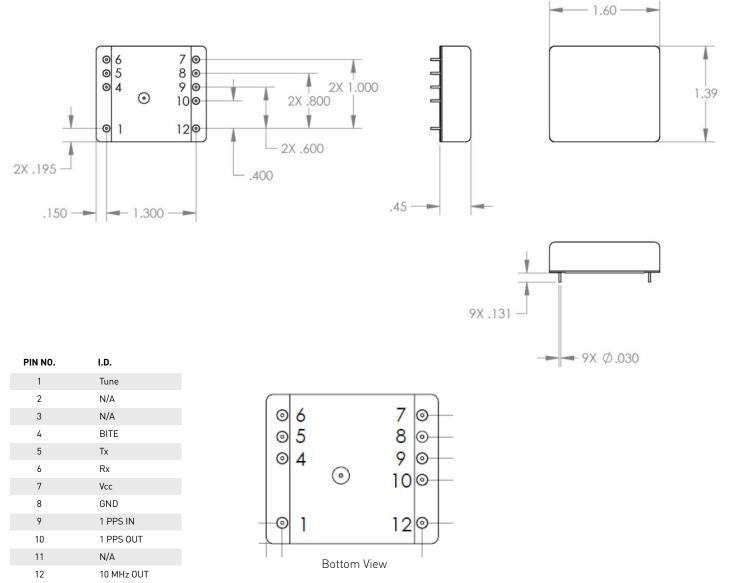
Options to Meet a Wider Range of Applications

The standard SA.45s CSAC option 001 provides an output frequency of 10MHz. However, other output frequencies are available: option 003 provides 16.384 MHz, and option 004 provides 10.24 MHz and option 006 provides a 5 MHz output.

For other output frequencies please contact Microsemi for details.

The Chip Scale Atomic Clock is not tested, qualified, and rated for space applications.

Mechanical Interface





Power Matters."

Quantum[™] SA.45s CSAC Option 001

Part number 090-00218-001

Specifications

All specifications at 25°C, Vcc =3.3V DC unless otherwise specified

ELECTRICAL SPECIFICATIONS

RF Output

- Frequency:	10 MHz
- Format:	CMOS
- Amplitude:	OV to Vcc
- Load impedance:	1 MΩ
- Quantity:	1

1 PPS Output

• • • •	
 Rise/fall time (10%-90%) at load capacitance 10pF: 	<10 ns
- Pulse width:	100 µs
- Level:	OV to Vcc
- Logic High (VoH) min:	2.80 V
- Logic Low (VoL) max:	0.30 V
- Load impedance:	1 MΩ
- Quantity:	1

1 PPS Input

Format:	Rising edge
Low level:	<0.5 V
High level:	2.5 V to Vcc
Input impedance:	1 MΩ
Quantity:	1

Serial Communications

- Protocol:	RS232
- Format:	CMOS OV to Vcc
- Tx/Rx impedance:	1 ΜΩ
- Baud rate:	57600

Built-in Test Equipment (BITE) output

- Format:	CMOS OV to Vcc
 Load impedance: 	1 ΜΩ
- Logic:	0 = Normal operation
	1 = Alarm

Power Input

- Operating:	<120 mW
- Warmup:	<140 mW
- Input voltage (Vcc):	3.3 ± 0.1 VDC

PHYSICAL SPECIFICATIONS

- Size:	1.6" x 1.39" x 0.45"
- Weight:	<35 g
- MTBF:	>100,000 hours

ENVIRONMENTAL SPECIFICATIONS

Operating:	
Operating	to

- Operating temperature:	-10°C to +35°C
- Maximum frequency change over operating temp range (max. rate of change 0.5 °C/minute):	±5x10 ⁻¹⁰
 Frequency change over allowable input voltage range: 	±4x10 ⁻¹⁰

±4x10-10

ENVIRONMENTAL SPECIFICATIONS (Continued)

- Magnetic sensitivity (≼2.0 Gauss):	±9x10 ⁻¹¹ /Gauss
- Radiated emissions.	Compliant to FCC part 15, Class B, when mounted properly onto host PCB.
- Vibration:	Maintains lock under MIL-STD-810, Method 514.5, Procedure 1, 7.7 grms
- Humidity:	0 to 95% RH per MIL-STD-810, Method 507.4.
Storage and Transport (non-o	perating): -55°C to +40°C
- Temperature:	
- Shock (1 ms half-sine):	1000 g
- Vibration:	MIL-STD-810, Method 514.5, Procedure 1, 7.7 grms
PERFORMANCE PARAM	ETERS
Stability (Allan Deviation)	
ADEV	
TAU = 1 sec	2.5x10 ⁻¹⁰
TAU = 10 sec	8x10 ⁻¹¹
TAU = 100 sec	2.5x10 ⁻¹¹
TAU = 1000 sec	8x10 ⁻¹²
RF Output Phase Noise (SSB)	

1 Hz	<-50 dBc/Hz
10 Hz	<-70 dBc/Hz
100 Hz	<-113 dBc/Hz
1000 Hz	<-128 dBc/Hz
10000 Hz	<-135 dBc/Hz
100,000 Hz	<-140 dBc/Hz

Frequency Accuracy

- Maximum offset at shipment:	±5x10 ⁻¹¹
- Maximum retrace (48 hrs off):	±5x10 ⁻¹⁰
- Aging, monthly*:	<9x10 ⁻¹⁰ typical
- Aging, yearly*:	<1x10 ⁻⁸ typical
- 1 PPS Sync.:	±100 ns
(*After 20 days of continuous energies	-)

(*After 30 days of continuous operation)

Digital Tuning

- Range:	±2x10 ⁻⁸
- Resolution:	1x10 ⁻¹²

Analog Tuning - Rango

Warm-up Time	<180 s
- Input:	0-2.5V into 100 kΩ
- Resolution:	1x10 ⁻¹¹
- Range:	±2.2x10 ⁻⁸

Solder

Hand solder using 63/37 Tin/Lead Solder with maximum soldering tip of 329°C (625°F)

±9x10⁻¹¹/Gauss

Compliant to FCC part 15, Class B, when mounted properly onto host PCB

Maintains lock under MIL-STD-810, method 514.5, procedure 1, 7.7 grms

0 to 95% RH per MIL-

-55°C to +40°C

1000 g

STD-810, method 507.4

MIL-STD-810, method 514.5, procedure 1, 7.7 grms



Quantum[™] SA.45s CSAC Option 003

Part number 090-00218-003

Specifications

voltage range:

All specifications at 25°C, Vcc = 3.3V DC unless otherwise specified

ELECTRICAL SPECIFICATIONS

ELECTRICAL SPECIFICATIONS	
RF Output	
- Frequency:	16.384 MHz
- Format:	CMOS
- Amplitude:	OV to Vcc
- Load impedance:	1 MΩ
- Quantity:	1
1 PPS Output	
- Rise/fall time (10%-90%) at load capacitance 10pF:	<10 ns
- Pulse width:	97.656 µs
- Level:	0V to Vcc
- Logic High (VOH) min:	2.80 V
- Logic Low (VOL) max:	0.30 V
- Load impedance:	1 MΩ
- Quantity:	1
	I
1 PPS Input	D
- Format:	Rising edge
- Low level:	<0.5 V
- High level:	2.5 V to Vcc
- Input impedance:	1 MΩ 1
- Quantity:	I
Serial Communications	
- Protocol:	RS-232
- Format:	CMOS OV to Vcc
- Tx/Rx impedance:	1 MΩ
- Baud rate:	57600
Built-in Test Equipment (BITE) output	
- Format:	CMOS OV to Vcc
- Load impedance:	1 ΜΩ
- Logic:	0 = Normal operation 1 = Alarm
Power Input	100
- Operating:	<120 mW
- Warmup:	<140 mW
- Input Voltage (Vcc):	3.3 ± 0.1 VDC
PHYSICAL SPECIFICATIONS	
- Size:	1.6" x 1.39" x 0.45"
- Weight:	<35 g
- MTBF:	>100,000 hours
ENVIRONMENTAL SPECIFICATIONS	
Operating:	
- Operating temperature:	-10°C to +35°C
- Maximum frequency change	
over operating temp range	
(max. rate of change 0.5°C/minute):	±5x10 ⁻¹⁰
- Frequency change over	
allowable input	
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±4x10-10

ENVIRONMENTAL SPECIFICATIONS (Continued)

- Magnetic sensitivity
- (≼2.0 Gauss): - Radiated emissions:

- Vibration:

- Humidity:

Storage and Transport (non-operating):

- Temperature:
 - Shock (1 ms half-sine):
 - Vibration:

PERFORMANCE PARAMETERS

Stability (Allan Deviation)

ADEV	
TAU = 1 sec	2.5x10 ⁻¹⁰
TAU = 10 sec	8x10 ⁻¹¹
TAU = 100 sec	2.5x10 ⁻¹¹
TAU = 1000 sec	8x10 ⁻¹²

RF Output Phase Noise (SSB)

1 Hz	<-46 dBc/Hz
10 Hz	<-66 dBc/Hz
100 Hz	<-110 dBc/Hz
1000 Hz	<-128 dBc/Hz
10000 Hz	<-135 dBc/Hz
100,000 Hz	<-140 dBc/Hz

Frequency Accuracy

- Maximum offset at shipment:	±5x10 ⁻¹¹
- Maximum retrace (48 hrs off):	±5x10 ⁻¹⁰
- Aging, monthly*:	<9x10 ⁻¹⁰ typical
- Aging, yearly*:	<1x10 ⁻⁸ typical
- 1 PPS Sync.:	±100 ns
(*After 30 days of continuous operation)	

Digital Tuning

- Range:	±2x10-8
- Resolution:	1x10 ⁻¹²
Analog Tuning	
- Range:	±2.2x10-8
- Resolution:	1x10 ⁻¹¹
- Input:	0-2.5V into 100 kΩ

Solder

Warm-up Time

Hand solder using 63/37 Tin/Lead Solder with maximum soldering tip of 329°C (625°F)

<180 s

±9x10⁻¹¹/Gauss

Compliant to FCC part 15, Class B, when mounted properly onto host PCB

Maintains lock under MIL-STD-810, method 514.5, procedure 1, 7.7 grms 0 to 95% RH per MIL-

STD-810, method 507.4

MIL-STD-810, method

514.5, procedure 1, 7.7 grms

-55°C to +40°C

1000 g



Power Matters."

Quantum[™] SA.45s CSAC Option 004

Part number 090-00218-004

Specifications

All specifications at 25°C, Vcc = 3.3V DC unless otherwise specified

ELECTRICAL SPECIFICATIONS

RF Output	10.24 MHz
- Frequency: - Format:	CMOS
- Amplitude:	OV to Vcc
	1 ΜΩ
- Load impedance:	1
- Quantity:	1
1 PPS Output	
- Rise/fall time (10%-90%)	<10 ns
at load capacitance 10pF: - Pulse width:	100 µs
- Level:	OV to Vcc
- Level: - Logic High (VOH) min:	2.80 V
	0.30 V
- Logic Low (VOL) max: - Load impedance:	0.30 V 1 MΩ
•	1
- Quantity:	1
1 PPS Input	
- Format:	Rising edge
- Low level:	<0.5 V
- High level:	2.5 V to Vcc
- Input impedance:	1 ΜΩ
- Quantity:	1
Serial Communications	
- Protocol:	RS-232
- Format:	CMOS 0V to Vcc
- Tx/Rx impedance:	1 ΜΩ
- Baud rate:	57600
Built-in Test Equipment (BITE) output	
- Format:	CMOS 0V to Vcc
- Load impedance:	1 ΜΩ
- Logic:	0 = Normal operation
-	1 = Alarm
Power Input	
- Operating:	<120 mW
- Warmup:	<140 mW
- Input Voltage (Vcc):	3.3 ± 0.1 VDC
PHYSICAL SPECIFICATIONS	
- Size:	1.6" x 1.39" x 0.45"
- Weight: - MTBF:	<35 g >100,000 hours
	>100,000 110015
ENVIRONMENTAL SPECIFICATIONS	
Operating:	1000 . 0500
- Operating temperature:	-10°C to +35°C
 Maximum frequency change over operating temp range 	
(max. rate of change	
0.5°C/minute):	±5x10 ⁻¹⁰
- Frequency change over	
allowable input	. (10-10
voltage range:	±4x10 ⁻¹⁰

ENVIRONMENTAL SPECIFICATIONS (Continued)

 ENVIRONMENTAL SPEC Magnetic sensitivity (<2.0 Gauss): Radiated emissions: 	IFICATIONS
- Vibration:	
- Humidity:	
Storage and Transport (non-og - Temperature: - Shock (1 ms half-sine): - Vibration:	perating):
PERFORMANCE PARAM	ETERS
Stability (Allan Deviation) ADEV TAU = 1 sec TAU = 10 sec TAU = 100 sec TAU = 1000 sec	2.5x10 ⁻¹⁰ 8x10 ⁻¹¹ 2.5x10 ⁻¹¹ 8x10 ⁻¹²

RF Output Phase Noise (SSB)

1 Hz	<-50 dBc/Hz
10 Hz	<-70 dBc/Hz
100 Hz	<-113 dBc/Hz
1000 Hz	<-128 dBc/Hz
10000 Hz	<-135 dBc/Hz
100.000 Hz	<-140 dBc/Hz

Frequency Accuracy

- Maximum offset at shipment:	±5x10 ⁻¹¹	
- Maximum retrace (48 hrs off):	±5x10 ⁻¹⁰	
- Aging, monthly*:	<9x10 ⁻¹⁰ typical	
- Aging, yearly*:	<1x10 ⁻⁸ typical	
- 1 PPS Sync.: ±100 ns		
(*After 30 days of continuous operation)		

Digital luning	
- Range:	±2x10-8
- Resolution:	1x10 ⁻¹²
. .	
Analog Tuning	
- Range:	±2.2x10-8
- Resolution:	1x10 ⁻¹¹
- Input:	0-2.5V into 100 kΩ
Warm-up Time	<180 s

Solder

Hand solder using 63/37 Tin/Lead Solder with maximum soldering tip of 329°C (625°F)



Quantum[™] SA.45s CSAC Option 006

Part number 090-00218-006

Specifications

All specifications at 25°C, Vcc = 3.3V DC unless otherwise specified

ELECTRICAL SPECIFICATIONS

RF Outptut	
- Frequency:	5 MHz
- Format:	CMOS
- Amplitude:	OV to Vcc
- Load impedance:	1 ΜΩ
- Quantity:	1
1 PPS Output	
- Rise/fall time (10%-90%)	
at load capacitance 10pF:	<10 ns
- Pulse width:	100 µs
- Level:	OV to Vcc
- Logic High (VOH) min:	2.80 V
- Logic Low (VOL) max:	0.30 V
- Load impedance:	1 ΜΩ
- Quantity:	1
1 PPS Input	
- Format:	Rising edge
- Low level:	<0.5 V
- High level:	2.5 V to Vcc
- Input impedance:	1 ΜΩ
- Quantity:	1
Serial Communications	
- Protocol:	RS-232
- Format:	CMOS OV to Vcc
- Tx/Rx impedance:	1 ΜΩ
- Baud rate:	57600
Built-in Test Equipment (BITE) output	
- Format:	CMOS 0V to Vcc
- Load impedance:	1 ΜΩ
- Logic:	0 = Normal operation 1 = Alarm
Power Input	
- Operating:	<120 mW
- Warmup:	<140 mW
- Input Voltage (Vcc):	3.3 ± 0.1 VDC
PHYSICAL SPECIFICATIONS	
- Size:	1.6" x 1.39" x 0.45"
- Weight:	<35 q
- MTBF:	>100,000 hours
ENVIRONMENTAL SPECIFICATIONS	
Operating:	
- Operating temperature:	-10°C to +35°C
- Maximum frequency change	
over operating temp range	
(max. rate of change 0.5°C/minute):	±5x10 ⁻¹⁰
	IJXIU
- Frequency change over allowable input	
voltage range:	±4x10 ⁻¹⁰

ENVIRONMENTAL SPECIFICATIONS (Continued)

- Magnetic sensitivity
(≤2.0 Gauss):
- Radiated emissions:

- Vibration:

- Humidity:

Storage and Transport (non-operating):

- Temperature:
- Shock (1 ms half-sine):
- Vibration:

PERFORMANCE PARAMETERS

Stability (Allan Deviation)

ADEV	
TAU = 1 sec	2.5x10 ⁻¹⁰
TAU = 10 sec	8x10 ⁻¹¹
TAU = 100 sec	2.5x10 ⁻¹¹
TAU = 1000 sec	8x10 ⁻¹²

RF Output Phase Noise (SSB)

1 Hz	<-53 dBc/Hz
10 Hz	<-73 dBc/Hz
100 Hz	<-116 dBc/Hz
1000 Hz	<-131 dBc/Hz
10000 Hz	<-138 dBc/Hz
100,000 Hz	<-140 dBc/Hz

Frequency Accuracy

- Maximum offset at shipment:	±5x10 ⁻¹¹	
- Maximum retrace (48 hrs off):	±5x10 ⁻¹⁰	
- Aging, monthly*:	<9x10 ⁻¹⁰ typical	
- Aging, yearly*:	<1x10 ⁻⁸ typical	
- 1 PPS Sync.:	±100 ns	
(*After 30 days of continuous operation)		

Digital Tuning

Warm-up Time	<180 s
Analog Tuning - Range: - Resolution: - Input:	±2.2x10 ⁻⁸ 1x10 ⁻¹¹ 0-2.5V into 100 kΩ
- Range: - Resolution:	±2x10 ⁻⁸ 1x10 ⁻¹²

Solder

Hand solder using 63/37 Tin/Lead Solder with maximum soldering tip of 329°C (625°F)

±9x10⁻¹¹/Gauss Compliant to FCC part 15, Class B, when mounted properly onto host PCB Maintains lock under MIL-STD-810, method 514.5, procedure 1, 7.7 grms 0 to 95% RH per MIL-STD-810, method 507.4

-55°C to +40°C 1000 g MIL-STD-810, method 514.5, procedure 1, 7.7 grms



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